

PROCESS OF REMOVING HOLEFILL RESIDUE FROM A
METALLIC SURFACE OF AN ELECTRONIC SUBSTRATE

ABSTRACT OF THE DISCLOSURE

- A process of removing holefill residue from a surface of an electronic substrate in
- 5 which the holefill residue is contacted with a swelling agent followed by planarizing of the surface in the presence of an agent no stronger than a liquid having a pH of about 6 to about 8.